

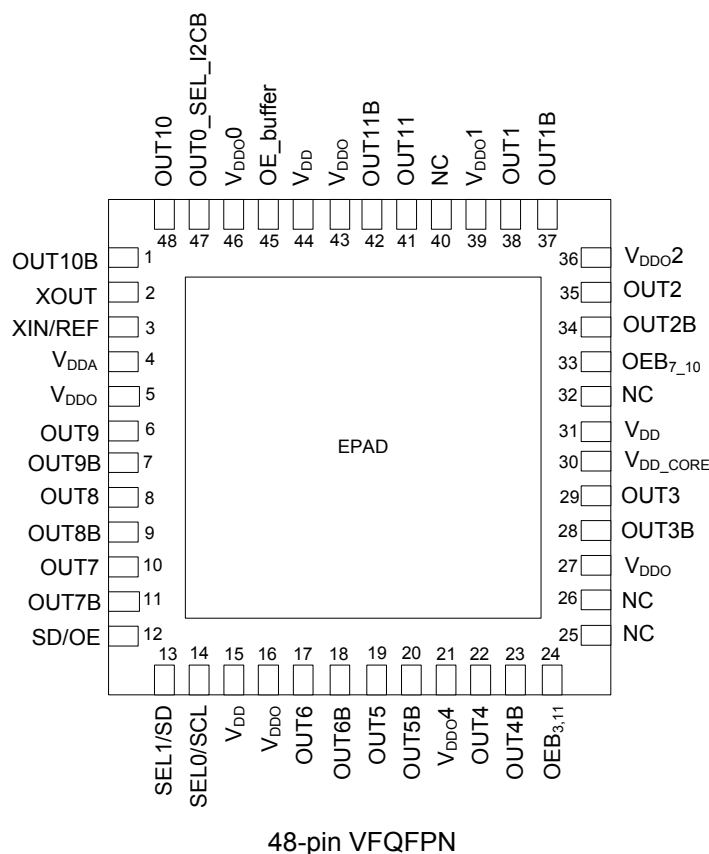
Description

The 5P49V5908 is a programmable clock generator intended for high performance consumer, networking, industrial, computing, and data-communications applications. Configurations may be stored in on-chip One-Time Programmable (OTP) memory or changed using I²C interface. This is IDT's fifth generation of programmable clock technology (VersaClock[®] 5).

The frequencies are generated from a single reference clock or crystal. Two select pins allow up to 4 different configurations to be programmed and accessible using processor GPIOs or bootstrapping. The different selections may be used for different operating modes (full function, partial function, partial power-down), regional standards (US, Japan, Europe) or system production margin testing.

The device may be configured to use one of two I²C addresses to allow multiple devices to be used in a system.

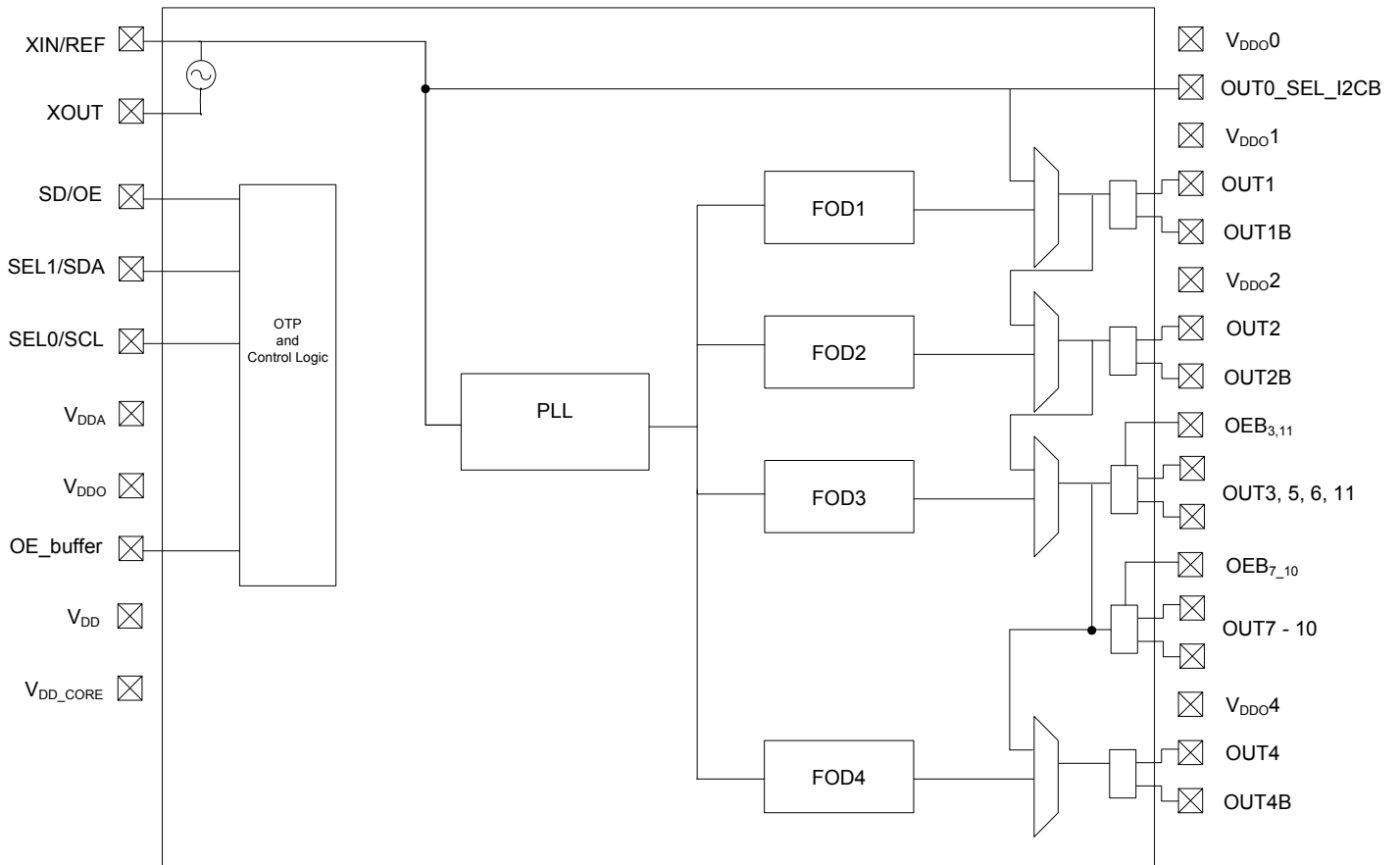
Pin Assignment



Features

- Generates up to four independent output frequencies with a total of 11 differential outputs and one reference output
- Supports multiple differential output I/O standards:
 - Three universal outputs pairs with each configurable as one differential output pair (LVDS, LVPECL or regular HCSL) or two LVCMOS outputs. Frequency of each output pair can be individually programmed
 - Eight copies of Low Power HCSL(LP-HCSL) outputs. Programmable frequency
 - See Output Features and Descriptions for details
- One reference LVCMOS output clock
- High performance, low phase noise PLL, < 0.7 ps RMS typical phase jitter on outputs:
 - PCIe Gen1, 2, 3 compliant clock capability
 - USB 3.0 compliant clock capability
 - 1 GbE and 10 GbE
- Four fractional output dividers (FODs)
- Independent Spread Spectrum capability from each fractional output divider (FOD)
- Four banks of internal non-volatile in-system programmable or factory programmable OTP memory
- I²C serial programming interface
- Input frequency ranges:
 - LVCMOS Reference Clock Input (XIN/REF) – 1MHz to 200MHz
 - Crystal frequency range: 8MHz to 40MHz
- Output frequency ranges:
 - LVCMOS Clock Outputs – 1MHz to 200MHz
 - LP-HCSL Clock Outputs – 1MHz to 200MHz
 - Other Differential Clock Outputs – 1MHz to 350MHz
- Programmable loop bandwidth
- Programmable crystal load capacitance
- Power-down mode
- Mixed voltage operation:
 - 1.8V core
 - 1.8V VDDO for 8 LP-HCSL outputs
 - 1.8V to 3.3V VDDO for other outputs (3 programmable differential outputs and 1 reference output)
 - See Pin Descriptions for details
- Available in 48-pin VFQFPN package (NDG48)
- -40° to +85°C industrial temperature operation

Functional Block Diagram



Typical Applications

- Ethernet switch/router
- PCI Express 1.0/2.0/3.0
- Broadcast video/audio timing
- Multi-function printer
- Processor and FPGA clocking
- Any-frequency clock conversion
- MSAN/DSLAM/PON
- Fiber Channel, SAN
- Telecom line cards
- 1 GbE and 10 GbE

Table 1: Pin Descriptions

| Number | Name | Type | | Description |
|--------|---------------------|--------|--------------------|--|
| 1 | OUT10B | Output | | Complementary output clock 10. Low-Power HCSL (LP-HCSL) output. |
| 2 | XOUT | Input | | Crystal oscillator interface output. |
| 3 | XIN/REF | Input | | Crystal oscillator interface input, or single-ended LVCMOS clock input. Ensure that the input voltage is 1.2V max. Refer to the section "Overdriving the XIN/REF Interface". |
| 4 | VDDA | Power | | Analog functions power supply pin. Connect to 1.8V. |
| 5 | VDDO | Power | | Connect to 1.8V. Power pin for outputs 3, 5-11. |
| 6 | OUT9 | Output | | Output clock 9. Low-Power HCSL (LP-HCSL) output. |
| 7 | OUT9B | Output | | Complementary output clock 9. Low-Power HCSL (LP-HCSL) output. |
| 8 | OUT8 | Output | | Output clock 8. Low-Power HCSL (LP-HCSL) output. |
| 9 | OUT8B | Output | | Complementary output clock 8. Low-Power HCSL (LP-HCSL) output. |
| 10 | OUT7 | Output | | Output clock 7. Low-Power HCSL (LP-HCSL) output. |
| 11 | OUT7B | Output | | Complementary output clock 7. Low-Power HCSL (LP-HCSL) output. |
| 12 | SD/OE | Input | Internal Pull-down | Enables/disables the outputs (OE) or powers down the chip (SD). The SH bit controls the configuration of the SD/OE pin. The SH bit needs to be high for SD/OE pin to be configured as SD. The SP bit (0x02) controls the polarity of the signal to be either active HIGH or LOW only when pin is configured as OE (Default is active LOW.) Weak internal pull down resistor. When configured as SD, device is shut down, differential outputs are driven high/low, and the single-ended LVCMOS outputs are driven low. When configured as OE, and outputs are disabled, the outputs can be selected to be tri-stated or driven high/low, depending on the programming bits as shown in the SD/OE Pin Function Truth table. |
| 13 | SEL1/SDA | Input | Internal Pull-down | Configuration select pin, or I2C SDA input as selected by OUT0_SEL_I2CB. Weak internal pull down resistor. |
| 14 | SEL0/SCL | Input | Internal Pull-down | Configuration select pin, or I2C SCL input as selected by OUT0_SEL_I2CB. Weak internal pull down resistor. |
| 15 | VDD | Power | | Connect to 1.8V. |
| 16 | VDDO | Power | | Connect to 1.8V. Power pin for outputs 3, 5-11. |
| 17 | OUT6 | Output | | Output Clock 6. Low-Power HCSL (LP-HCSL) output. |
| 18 | OUT6B | Output | | Complementary Output Clock 6. Low-Power HCSL (LP-HCSL) output. |
| 19 | OUT5 | Output | | Output Clock 5. Low-Power HCSL (LP-HCSL) output. |
| 20 | OUT5B | Output | | Complementary output clock 5. Low-Power HCSL (LP-HCSL) output. |
| 21 | VDDO4 | Power | | Connect to 1.8V to 3.3V. VDD supply for OUT4. |
| 22 | OUT4 | Output | | Output clock 4. Please refer to the Output Drivers section for more details. |
| 23 | OUT4B | Output | | Complementary output clock 4. Please refer to the Output Drivers section for more details. |
| 24 | OEB _{3,11} | Input | Internal Pull-down | Active low Output Enable pin for Outputs 3, 5, 6, 11. 1 = disable outputs, 0 = enable outputs. This pin has internal pull-down. |
| 25 | NC | Input | — | Do not connect. |
| 26 | NC | Input | — | Do not connect. |
| 27 | VDDO | Power | | Connect to 1.8V. Power pin for outputs 3, 5-11. |
| 28 | OUT3B | Output | | Complementary output Clock 3. Low-Power HCSL (LP-HCSL) output. |
| 29 | OUT3 | Output | | Output clock 3. Low-Power HCSL (LP-HCSL) output. |
| 30 | VDD_Core | Power | | Connect to 1.8V. |
| 31 | VDD | Power | | Connect to 1.8V. |
| 32 | NC | Input | | Do not connect. |
| 33 | OEB _{7,10} | Input | Internal Pull-down | Active low Output Enable pin for Outputs 7-10. 1 = disable outputs, 0 = enable outputs. This pin has internal pull-down. |
| 34 | OUT2B | Output | | Complementary output clock 2. Please refer to the Output Drivers section for more details. |
| 35 | OUT2 | Output | | Output clock 2. Please refer to the Output Drivers section for more details. |
| 36 | VDDO2 | Power | | Connect to 1.8V to 3.3V. VDD supply for OUT2 |
| 37 | OUT1B | Output | | Complementary output clock 1. Please refer to the Output Drivers section for more details. |

Pin Descriptions (cont.)

| Number | Name | Type | | Description |
|--------|---------------|--------|--------------------|--|
| 38 | OUT1 | Output | | Output clock 1. Please refer to the Output Drivers section for more details. |
| 39 | VDDO1 | Power | | Connect to 1.8V to 3.3V. VDD supply for OUT1 |
| 40 | NC | Input | — | Do not connect. |
| 41 | OUT11 | Output | | Output clock 11. Low-Power HCSSL(LP-HCSSL) output. |
| 42 | OUT11B | Output | | Complementary output clock 11. Low-Power HCSSL(LP-HCSSL) output. |
| 43 | VDDO | Power | | Connect to 1.8V. Power pin for outputs 3, 5-11 |
| 44 | VDD | Power | | Connect to 1.8V |
| 45 | OE_buffer | Input | Internal Pull-up | Active High Output enable for outputs 3, 5-11. 0 = disable outputs, 1=enable outputs. This pin has internal pull-up. |
| 46 | VDDO0 | Power | | Power supply pin for OUT0_SEL_I2CB. Connect to 1.8 to 3.3V. Sets output voltage levels for OUT0. |
| 47 | OUT0_SEL_I2CB | Output | Internal Pull-down | Latched input/LVCMOS Output. At power up, the voltage at the pin OUT0_SEL_I2CB is latched by the part and used to select the state of pins 13 and 14. If a weak pull up (10Kohms) is placed on OUT0_SEL_I2CB, pins 13 and 14 will be configured as hardware select pins, SEL1 and SEL0. If a weak pull down (10Kohms) is placed on OUT0_SEL_I2CB or it is left floating, pins 13 and 14 will act as the SDA and SCL pins of an I2C interface. After power up, the pin acts as a LVCMOS reference output. |
| 48 | OUT10 | Output | | Output clock 10. Low-Power HCSSL (LP-HCSSL) output. |
| EPAD | GND | GND | | Connect to ground pad. |

PLL Features and Descriptions

Spread Spectrum

To help reduce electromagnetic interference (EMI), the 5P49V5908 supports spread spectrum modulation. The output clock frequencies can be modulated to spread energy across a broader range of frequencies, lowering system EMI. The 5P49V5908 implements spread spectrum using the Fractional-N output divide, to achieve controllable modulation rate and spreading magnitude. The Spread spectrum can be applied to any output divider and any spread amount from $\pm 0.25\%$ to $\pm 2.5\%$ center spread and -0.5% to -5% down spread.

Table 2: Loop Filter

PLL loop bandwidth range depends on the input reference frequency (Fref) and can be set between the loop bandwidth range as shown in the table below.

| Input Reference Frequency—Fref (MHz) | Loop Bandwidth Min (kHz) | Loop Bandwidth Max (kHz) |
|--------------------------------------|--------------------------|--------------------------|
| 5 | 40 | 126 |
| 350 | 300 | 1000 |

Table 3: Configuration Table

This table shows the SEL1, SEL0 settings to select the configuration stored in OTP. Four configurations can be stored in OTP. These can be factory programmed or user programmed.

| OUT0_SEL_I2CB @ POR | SEL1 | SEL0 | I ² C Access | REG0:7 | Config |
|---------------------|------|------|-------------------------|--------|--------------|
| 1 | 0 | 0 | No | 0 | 0 |
| 1 | 0 | 1 | No | 0 | 1 |
| 1 | 1 | 0 | No | 0 | 2 |
| 1 | 1 | 1 | No | 0 | 3 |
| 0 | X | X | Yes | 1 | I2C defaults |
| 0 | X | X | Yes | 0 | 0 |

At power up time, the SEL0 and SEL1 pins must be tied to either the VDDA power supply so that they ramp with that supply or are tied low (this is the same as floating the pins). This will cause the register configuration to be loaded that is selected according to Table 3 above. Providing that OUT0_SEL_I2CB was 1 at POR and OTP register 0:7=0, after the first 10ms of operation the levels of the SELx pins can be changed, either to low or to the same level as VDDA. The SELx pins must be driven with a digital signal of < 300ns Rise/Fall time and only a single pin can be changed at a time. After a pin level change, the device must not be interrupted for at least 1ms so that the new values have time to load and take effect.

If OUT0_SEL_I2CB was 0 at POR, alternate configurations can only be loaded via the I2C interface.

Crystal Input (XIN/REF)

The crystal used should be a fundamental mode quartz crystal; overtone crystals should not be used.

A crystal manufacturer will calibrate its crystals to the nominal frequency with a certain load capacitance value. When the oscillator load capacitance matches the crystal load capacitance, the oscillation frequency will be accurate. When the oscillator load capacitance is lower than the crystal load capacitance, the oscillation frequency will be higher than nominal and vice versa so for an accurate oscillation frequency you need to make sure to match the oscillator load capacitance with the crystal load capacitance.

To set the oscillator load capacitance there are two tuning capacitors in the IC, one at XIN and one at XOUT. They can be adjusted independently but commonly the same value is used for both capacitors. The value of each capacitor is composed of a fixed capacitance amount plus a variable capacitance amount set with the XTAL[5:0] register. Adjustment of the crystal tuning capacitors allows for maximum flexibility to accommodate crystals from various manufacturers. The range of tuning capacitor values available are in accordance with the following table.

XTAL[5:0] Tuning Capacitor Characteristics

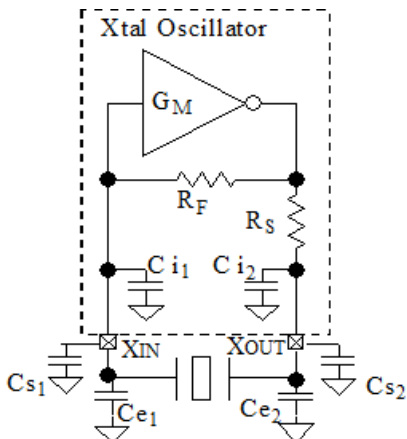
| Parameter | Bits | Step (pF) | Min (pF) | Max (pF) |
|-----------|------|-----------|----------|----------|
| XTAL | 6 | 0.5 | 9 | 25 |

The capacitance at each crystal pin inside the chip starts at 9pF with setting 000000b and can be increased up to 25pF with setting 111111b. The step per bit is 0.5pF.

You can write the following equation for this capacitance:

$$C_i = 9\text{pF} + 0.5\text{pF} \times \text{XTAL}[5:0]$$

The PCB where the IC and the crystal will be assembled adds some stray capacitance to each crystal pin and more capacitance can be added to each crystal pin with additional external capacitors.



You can write the following equations for the total capacitance at each crystal pin:

$$C_{XIN} = C_{i1} + C_{s1} + C_{e1}$$

$$C_{XOUT} = C_{i2} + C_{s2} + C_{e2}$$

C_{i1} and C_{i2} are the internal, tunable capacitors. C_{s1} and C_{s2} are stray capacitances at each crystal pin and typical values are between 1pF and 3pF.

C_{e1} and C_{e2} are additional external capacitors that can be added to increase the crystal load capacitance beyond the tuning range of the internal capacitors. However, increasing the load capacitance reduces the oscillator gain so please consult the factory when adding C_{e1} and/or C_{e2} to avoid crystal startup issues. C_{e1} and C_{e2} can also be used to adjust for unpredictable stray capacitance in the PCB.

The final load capacitance of the crystal:

$$C_L = C_{XIN} \times C_{XOUT} / (C_{XIN} + C_{XOUT})$$

For most cases it is recommended to set the value for capacitors the same at each crystal pin:

$$C_{XIN} = C_{XOUT} = C_x \rightarrow C_L = C_x / 2$$

The complete formula when the capacitance at both crystal pins is the same:

$$C_L = (9\text{pF} + 0.5\text{pF} \times \text{XTAL}[5:0] + C_s + C_e) / 2$$

Example 1: The crystal load capacitance is specified as 8pF and the stray capacitance at each crystal pin is $C_s=1.5\text{pF}$. Assuming equal capacitance value at XIN and XOUT, the equation is as follows:

$$8\text{pF} = (9\text{pF} + 0.5\text{pF} \times \text{XTAL}[5:0] + 1.5\text{pF}) / 2 \rightarrow$$

$$0.5\text{pF} \times \text{XTAL}[5:0] = 5.5\text{pF} \rightarrow \text{XTAL}[5:0] = 11 \text{ (decimal)}$$

Example 2: The crystal load capacitance is specified as 12pF and the stray capacitance C_s is unknown. Footprints for external capacitors C_e are added and a worst case C_s of 5pF is used. For now we use $C_s + C_e = 5\text{pF}$ and the right value for C_e can be determined later to make 5pF together with C_s .

$$12\text{pF} = (9\text{pF} + 0.5\text{pF} \times \text{XTAL}[5:0] + 5\text{pF}) / 2 \rightarrow$$

$$\text{XTAL}[5:0] = 20 \text{ (decimal)}$$

OTP Interface

The 5P49V5908 can also store its configuration in an internal OTP. The contents of the device's internal programming registers can be saved to the OTP by setting `burn_start` (W114[3]) to high and can be loaded back to the internal programming registers by setting `usr_rd_start`(W114[0]) to high.

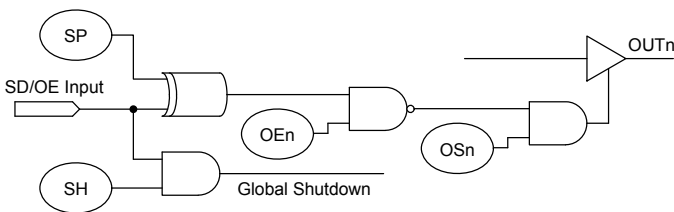
To initiate a save or restore using I²C, only two bytes are transferred. The device address is issued with the read/write bit set to “0”, followed by the appropriate command code. The save or restore instruction executes after the STOP condition is issued by the Master, during which time the 5P49V5908 will not generate Acknowledge bits. The 5P49V5908 will acknowledge the instructions after it has completed execution of them. During that time, the I²C bus should be interpreted as busy by all other users of the bus.

On power-up of the 5P49V5908, an automatic restore is performed to load the OTP contents into the internal programming registers. The 5P49V5908 will be ready to accept a programming instruction once it acknowledges its 7-bit I²C address.

Availability of primary and secondary I²C addresses to allow programming for multiple devices in a system. The I²C slave address can be changed from the default 0xD4 to 0xD0 by programming the I2C_ADDR bit D0. *VersaClock 5 Programming Guide* provides detailed I²C programming guidelines and register map.

SD/OE Pin Function

The polarity of the SD/OE signal pin can be programmed to be either active HIGH or LOW with the SP bit (W16[1]). When SP is “0” (default), the pin becomes active LOW and when SP is “1”, the pin becomes active HIGH. The SD/OE pin can be configured as either to shutdown the PLL or to enable/disable the outputs. The SH bit controls the configuration of the SD/OE pin. The SH bit needs to be high for SD/OE pin to be configured as SD.



When configured as SD, device is shut down, differential outputs are driven High/Low, and the single-ended LVCMOS outputs are driven low. When configured as OE, and outputs are disabled, the outputs are driven high/low.

Table 4: SD/OE Pin Function Truth Table

| SH bit | SP bit | OSn bit | OEn bit | SD/OE | OUTn |
|--------|--------|---------|---------|-------|-------------------------------------|
| 0 | 0 | 0 | x | x | Tri-state ² |
| 0 | 0 | 1 | 0 | x | Output active |
| 0 | 0 | 1 | 1 | 0 | Output active |
| 0 | 0 | 1 | 1 | 1 | Output driven High Low |
| 0 | 1 | 0 | x | x | Tri-state ² |
| 0 | 1 | 1 | 0 | x | Output active |
| 0 | 1 | 1 | 1 | 0 | Output driven High Low |
| 0 | 1 | 1 | 1 | 1 | Output active |
| 1 | 0 | 0 | x | 0 | Tri-state ² |
| 1 | 0 | 1 | 0 | 0 | Output active |
| 1 | 0 | 1 | 1 | 0 | Output active |
| 1 | 1 | 0 | x | 0 | Tri-state ² |
| 1 | 1 | 1 | 0 | 0 | Output active |
| 1 | 1 | 1 | 1 | 0 | Output driven High Low |
| 1 | x | x | x | 1 | Output driven High Low ¹ |

Note 1 : Global Shutdown

Note 2 : Tri-state regardless of OEn bits

Output Alignment

Each output divider block has a synchronizing POR pulse to provide startup alignment between outputs. This allows alignment of outputs for low skew performance. The phase alignment works both for integer output divider values and for fractional output divider values.

Besides the POR at power up, the same synchronization reset is also triggered when switching between configurations with the SEL0/1 pins. This ensures that the outputs remain aligned in every configuration. This reset causes the outputs to suspend for a few hundred microseconds so the switchover is not glitch-less. The reset can be disabled for applications where glitch-less switch over is required and alignment is not critical.

When using I²C to reprogram an output divider during operation, alignment can be lost. Alignment can be restored by manually triggering the reset through I²C.

When alignment is required for outputs with different frequencies, the outputs are actually aligned on the falling edges of each output by default. Rising edge alignment can also be achieved by utilizing the programmable skew feature to delay the faster clock by 180 degrees. The programmable skew feature also allows for fine tuning of the alignment.

For details of register programming, please see [VersaClock 5 Family Register Descriptions and Programming Guide](#) for details.

Output Divides

Each of the four output divides are comprised of a 12-bit integer counter, and a 24-bit fractional counter. The output divide can operate in integer divide only mode for improved performance, or utilize the fractional counters to generate any frequency with a synthesis accuracy better than 50ppb.

The Output Divide also has the capability to apply a spread modulation to the output frequency. Independent of output frequency, a triangle wave modulation between 30 and 63kHz may be generated.

Output Skew

For outputs that share a common output divide value, there will be the ability to skew outputs by quadrature values to minimize interaction on the PCB. The skew on each output can be adjusted from 0 to 360 degrees. Skew is adjusted in units equal to 1/32 of the VCO period. So, for 100 MHz output and a 2800 MHz VCO, you can select how many 11.161ps units you want added to your skew (resulting in units of 0.402 degrees). For example, 0, 0.402, 0.804, 1.206, 1.408, and so on. The granularity of the skew adjustment is always dependent on the VCO period and the output period.

Output Drivers

The OUT1 to OUT4 clock outputs are provided with register-controlled output drivers. By selecting the output drive type in the appropriate register, any of these outputs can support LVCMOS, LVPECL, HCSL or LVDS logic levels

The operating voltage ranges of each output is determined by its independent output power pin (V_{DDO}) and thus each can have different output voltage levels. Output voltage levels of 2.5V or 3.3V are supported for differential HCSL, LVPECL operation, and 1.8V, 2.5V, or 3.3V are supported for LVCMOS and differential LVDS operation.

Each output may be enabled or disabled by register bits. When disabled an output will be in a logic 0 state as determined by the programming bit table shown on page 6.

LVCMOS Operation

When a given output is configured to provide LVCMOS levels, then both the OUT_x and OUT_xB outputs will toggle at the selected output frequency. All the previously described configuration and control apply equally to both outputs. Frequency, phase alignment, voltage levels and enable / disable status apply to both the OUT_x and OUT_xB pins. The OUT_x and OUT_xB outputs can be selected to be phase-aligned with each other or inverted relative to one another by register programming bits. Selection of phase-alignment may have negative effects on the phase noise performance of any part of the device due to increased simultaneous switching noise within the device.

Device Start-up & Reset Behavior

The 5P49V5908 has an internal power-up reset (POR) circuit. The POR circuit will remain active for a maximum of 10ms after device power-up.

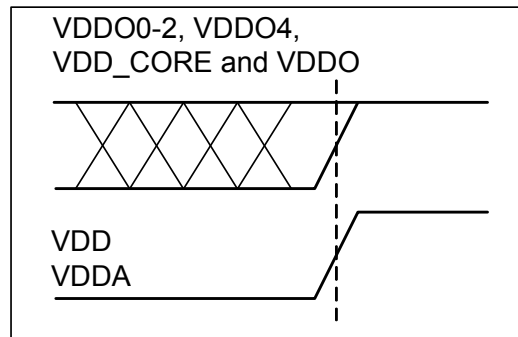
Upon internal POR circuit expiring, the device will exit reset and begin self-configuration.

The device will load internal registers using the configuration stored in the internal One-Time Programmable (OTP) memory.

Once the full configuration has been loaded, the device will respond to accesses on the serial port and will attempt to lock the PLL to the selected source and begin operation.

Power Up Ramp Sequence

VDDA and VDD must ramp up together. VDDO-2, VDDO4, VDD_CORE and VDDO must ramp up before, or concurrently with, VDDA and VDD. All power supply pins must be connected to a power rail even if the output is unused. All power supplies must ramp in a linear fashion and ramp monotonically.



I²C Mode Operation

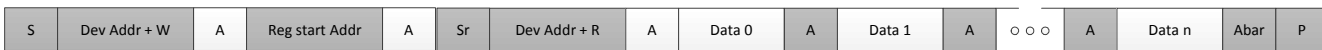
The device acts as a slave device on the I²C bus using one of the two I²C addresses (0xD0 or 0xD4) to allow multiple devices to be used in the system. The interface accepts byte-oriented block write and block read operations. Two address bytes specify the register address of the byte position of the first register to write or read. Data bytes (registers) are accessed in sequential order from the lowest to the highest byte (most significant bit first). Read and write block transfers can be stopped after any complete byte transfer. During a write operation, data will not be moved into the registers until the STOP bit is received, at which point, all data received in the block write will be written simultaneously.

For full electrical I²C compliance, it is recommended to use external pull-up resistors for SDATA and SCLK. The internal pull-down resistors have a size of 100k Ω typical.

Current Read



Sequential Read



Sequential Write



- from master to slave
- from slave to master
- S = start
- Sr = repeated start
- A = acknowledge
- Abar = none acknowledge
- P = stop

I²C Slave Read and Write Cycle Sequencing

Table 5: I²C Bus DC Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------|-----------------------|------------------------------------|-----------|-----|------------------|------|
| V _{IH} | Input HIGH Level | For SEL1/SDA pin and SEL0/SCL pin. | 0.7xVDDD | | 5.5 ² | V |
| V _{IL} | Input LOW Level | For SEL1/SDA pin and SEL0/SCL pin. | GND-0.3 | | 0.3xVDDD | V |
| V _{HYS} | Hysteresis of Inputs | | 0.05xVDDD | | | V |
| I _{IN} | Input Leakage Current | | -1 | | 30 | μA |
| V _{OL} | Output LOW Voltage | I _{OL} = 3 mA | | | 0.4 | V |

Table 6: I²C Bus AC Characteristics

| Symbol | Parameter | Min | Typ | Max | Unit |
|-----------------------|--|-------------------------|-----|-----|------|
| F _{SCLK} | Serial Clock Frequency (SCL) | 10 | | 400 | kHz |
| t _{BUF} | Bus free time between STOP and START | 1.3 | | | μs |
| t _{SU:START} | Setup Time, START | 0.6 | | | μs |
| t _{HD:START} | Hold Time, START | 0.6 | | | μs |
| t _{SU:DATA} | Setup Time, data input (SDA) | 100 | | | ns |
| t _{HD:DATA} | Hold Time, data input (SDA) ¹ | 0 | | | μs |
| t _{OVD} | Output data valid from clock | | | 0.9 | μs |
| C _B | Capacitive Load for Each Bus Line | | | 400 | pF |
| t _R | Rise Time, data and clock (SDA, SCL) | 20 + 0.1xC _B | | 300 | ns |
| t _F | Fall Time, data and clock (SDA, SCL) | 20 + 0.1xC _B | | 300 | ns |
| t _{HIGH} | HIGH Time, clock (SCL) | 0.6 | | | μs |
| t _{LOW} | LOW Time, clock (SCL) | 1.3 | | | μs |
| t _{SU:STOP} | Setup Time, STOP | 0.6 | | | μs |

Note 1: A device must internally provide a hold time of at least 300ns for the SDA signal (referred to the V_{IH}(MIN) of the SCL signal) to bridge the undefined region of the falling edge of SCL.

Note 2: I2C inputs are 5V tolerant.

Table 7: Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 5P49V5908. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

| Item | Rating |
|---|---------------------------|
| Supply Voltage, V_{DDA} , V_{DDD} , V_{DDO} | 3.465V |
| Inputs XIN/REF | 0V to 1.2V voltage swing |
| Outputs, V_{DDO} (LVCMOS) | -0.5V to $V_{DDO} + 0.5V$ |
| Outputs, I_O (SDA) | 10mA |
| Package Thermal Impedance, θ_{JA} | 42°C/W (0 mps) |
| Package Thermal Impedance, θ_{JC} | 41.8°C/W (0 mps) |
| Storage Temperature, T_{STG} | -65°C to 150°C |
| ESD Human Body Model | 2000V |
| Junction Temperature | 125°C |

Table 8: Recommended Operation Conditions

| Symbol | Parameter | Min | Typ | Max | Unit |
|-----------------|---|------|-----|------|------|
| V_{DDX} | Power supply voltage for supporting 1.8V outputs | 1.71 | 1.8 | 1.89 | V |
| V_{DDA} | Analog power supply voltage. Use filtered analog power supply if available. | 1.71 | | 1.89 | V |
| T_A | Operating temperature, ambient | -40 | | 85 | °C |
| C_{LOAD_OUT} | Maximum load capacitance (3.3V LVCMOS only) | | | 15 | pF |
| F_{IN} | External reference crystal | 8 | | 40 | MHz |
| t_{PU} | Power up time for all VDDs to reach minimum specified voltage (power ramps must be monotonic) | 0.05 | | 5 | ms |

Table 9: Input Capacitance, LVCMOS Output Impedance, and Internal Pull-down Resistance ($T_A = +25^\circ\text{C}$)

| Symbol | Parameter | Min | Typ | Max | Unit |
|--------------------|---|-----|-----|-----|------------|
| C_{IN} | Input Capacitance (SD/OE, SEL1/SDA, SEL0/SCL) | | 3 | 7 | pF |
| Pull-down Resistor | | 100 | | 300 | k Ω |
| R_{OUT} | LVCMOS Output Driver Impedance ($V_{DDO} = 1.8V, 2.5V, 3.3V$) | | 17 | | Ω |
| XIN/REF | Programmable capacitance at XIN/REF | 9 | | 25 | pF |
| XOUT | Programmable capacitance at XOUT | 9 | | 25 | pF |

Table 10:Crystal Characteristics

| Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|---|-----------------|-------------|---------|---------|----------|
| Mode of Oscillation | | Fundamental | | | |
| Frequency | | 8 | 25 | 40 | MHz |
| Equivalent Series Resistance (ESR) | | | 10 | 100 | Ω |
| Shunt Capacitance | | | | 7 | pF |
| Load Capacitance (CL) @ ≤ 25 MHz | | 6 | 8 | 12 | pF |
| Load Capacitance (CL) > 25 MHz to 40M | | 6 | | 8 | pF |
| Maximum Crystal Drive Level | | | | 100 | μ W |

Note: Typical crystal used is [FOX 603-25-150](http://www.foxonline.com). For different reference crystal options please go to www.foxonline.com.

Table 11: DC Electrical Characteristics

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Unit |
|--|------------------------------|--|-----|-----|-----|------|
| Iddcore ³ | Core Supply Current | 100 MHz on all outputs, 25 MHz REFCLK | | 44 | | mA |
| Iddox | Output Buffer Supply Current | LVPECL, 350MHz, 3.3V VDDOx | | 42 | 47 | mA |
| | | LVPECL, 350MHz, 2.5V VDDOx | | 37 | 42 | mA |
| | | LVDS, 350MHz, 3.3V VDDOx | | 18 | 21 | mA |
| | | LVDS, 350MHz, 2.5V VDDOx | | 17 | 20 | mA |
| | | LVDS, 350MHz, 1.8V VDDOx | | 16 | 19 | mA |
| | | HCSL, 250MHz, 3.3V VDDOx, 2 pF load | | 29 | 33 | mA |
| | | HCSL, 250MHz, 2.5V VDDOx, 2 pF load | | 28 | 33 | mA |
| | | LVC MOS, 50MHz, 3.3V, VDDOx ^{1,2} | | 16 | 18 | mA |
| | | LVC MOS, 50MHz, 2.5V, VDDOx ^{1,2} | | 14 | 16 | mA |
| | | LVC MOS, 50MHz, 1.8V, VDDOx ^{1,2} | | 12 | 14 | mA |
| | | LVC MOS, 200MHz, 3.3V VDDOx ¹ | | 36 | 42 | mA |
| | | LVC MOS, 200MHz, 2.5V VDDOx ^{1,2} | | 27 | 32 | mA |
| LVC MOS, 200MHz, 1.8V VDDOx ^{1,2} | | 16 | 19 | mA | | |
| Iddpd | Power Down Current | SD asserted, I2C Programming | | 10 | 14 | mA |

1. Single CMOS driver active.

2. Measured into a 5" 50 Ohm trace with 2 pF load.

3. Iddcore = IddA+ IddD, no loads.

Outputs Features and Descriptions

OUT1/OUT1B, OUT2/OUT2B, and OUT4/OUT4B can form three output pairs. Each output pair has individually programmable frequencies and can be configured as one differential pair (LVDS, LVPECL, regular HCSL) or two LVC MOS outputs. VDDO is individually selectable from 1.8V to 3.3V for LVDS and LVC MOS, and 2.5V to 3.3V for LVPECL and regular current-mode HCSL outputs.

OUT3, 5-11 are 8 Low-Power HCSL(LP-HCSL) differential output pairs. They are the same frequency which can be individually programmed. They utilize the 1.8V LP-HCSL technology which can reduce supply current and termination resistor count. LP-HCSL outputs are from 1MHz to 200MHz and other differential outputs are from 1MHz to 350MHz.

Table 12: DC Electrical Characteristics for 3.3V LVCMOS ($V_{DDO} = 3.3V \pm 5\%$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)¹

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Unit |
|--------|-----------------------------------|----------------------------------|----------------------|-----|----------------------|---------------|
| VOH | Output HIGH Voltage | IOH = -15mA | 2.4 | | VDDO | V |
| VOL | Output LOW Voltage | IOL = 15mA | | | 0.4 | V |
| IOZDD | Output Leakage Current (OUT1,2,4) | Tri-state outputs, VDDO = 3.465V | | | 5 | μA |
| IOZDD | Output Leakage Current (OUT0) | Tri-state outputs, VDDO = 3.465V | | | 30 | μA |
| VIH | Input HIGH Voltage | Single-ended inputs - SD/OE | $0.7 \times V_{DDD}$ | | $V_{DDD} + 0.3$ | V |
| VIL | Input LOW Voltage | Single-ended inputs - SD/OE | GND - 0.3 | | $0.3 \times V_{DDD}$ | V |
| VIH | Input HIGH Voltage | Single-ended input OUT0_SEL_I2CB | 2 | | $V_{DDO0} + 0.3$ | V |
| VIL | Input LOW Voltage | Single-ended input OUT0_SEL_I2CB | GND - 0.3 | | 0.4 | V |
| VIH | Input HIGH Voltage | Single-ended input - XIN/REF | 0.8 | | 1.2 | V |
| VIL | Input LOW Voltage | Single-ended input - XIN/REF | GND - 0.3 | | 0.4 | V |
| TR/TF | Input Rise/Fall Time | SD/OE, SEL1/SDA, SEL0/SCL | | | 300 | ns |

1. See "Recommended Operating Conditions" table.

Table 13: DC Electrical Characteristics for 2.5V LVCMOS ($V_{DDO} = 2.5V \pm 5\%$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Unit |
|--------|-----------------------------------|----------------------------------|----------------------|-----|----------------------|---------------|
| VOH | Output HIGH Voltage | IOH = -12mA | $0.7 \times V_{DDO}$ | | | V |
| VOL | Output LOW Voltage | IOL = 12mA | | | 0.4 | V |
| IOZDD | Output Leakage Current (OUT1,2,4) | Tri-state outputs, VDDO = 2.625V | | | 5 | μA |
| IOZDD | Output Leakage Current (OUT0) | Tri-state outputs, VDDO = 2.625V | | | 30 | μA |
| VIH | Input HIGH Voltage | Single-ended inputs - SD/OE | $0.7 \times V_{DDD}$ | | $V_{DDD} + 0.3$ | V |
| VIL | Input LOW Voltage | Single-ended inputs - SD/OE | GND - 0.3 | | $0.3 \times V_{DDD}$ | V |
| VIH | Input HIGH Voltage | Single-ended input OUT0_SEL_I2CB | 1.7 | | $V_{DDO0} + 0.3$ | V |
| VIL | Input LOW Voltage | Single-ended input OUT0_SEL_I2CB | GND - 0.3 | | 0.4 | V |
| VIH | Input HIGH Voltage | Single-ended input - XIN/REF | 0.8 | | 1.2 | V |
| VIL | Input LOW Voltage | Single-ended input - XIN/REF | GND - 0.3 | | 0.4 | V |
| TR/TF | Input Rise/Fall Time | SD/OE, SEL1/SDA, SEL0/SCL | | | 300 | ns |

Table 14: DC Electrical Characteristics for 1.8V LVCMOS ($V_{DDO} = 1.8V \pm 5\%$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Unit |
|------------|-----------------------------------|----------------------------------|------------------------|-----|-----------------------|---------------|
| V_{OH} | Output HIGH Voltage | IOH = -8mA | $0.7 \times V_{DDO}$ | | V_{DDO} | V |
| V_{OL} | Output LOW Voltage | IOL = 8mA | | | $0.25 \times V_{DDO}$ | V |
| I_{OZDD} | Output Leakage Current (OUT1,2,4) | Tri-state outputs, VDDO = 3.465V | | | 5 | μA |
| | Output Leakage Current (OUT0) | Tri-state outputs, VDDO = 3.465V | | | 30 | |
| V_{IH} | Input HIGH Voltage | Single-ended inputs - SD/OE | $0.7 \times V_{DDD}$ | | $V_{DDD} + 0.3$ | V |
| V_{IL} | Input LOW Voltage | Single-ended inputs - SD/OE | GND - 0.3 | | $0.3 \times V_{DDD}$ | V |
| V_{IH} | Input HIGH Voltage | Single-ended input OUT0_SEL_I2CB | $0.65 \times V_{DDO0}$ | | $V_{DDO0} + 0.3$ | V |
| V_{IL} | Input LOW Voltage | Single-ended input OUT0_SEL_I2CB | GND - 0.3 | | 0.4 | V |
| V_{IH} | Input HIGH Voltage | Single-ended input - XIN/REF | 0.8 | | 1.2 | V |
| V_{IL} | Input LOW Voltage | Single-ended input - XIN/REF | GND - 0.3 | | 0.4 | V |
| TR/TF | Input Rise/Fall Time | SEL0/SCL | | | 300 | ns |

Table 15: DC Electrical Characteristics for LVDS ($V_{DDO} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

| Symbol | Parameter | Min | Typ | Max | Unit |
|-----------------|---|-------|------|-------|------|
| $V_{OT}(+)$ | Differential Output Voltage for the TRUE binary state | 247 | | 454 | mV |
| $V_{OT}(-)$ | Differential Output Voltage for the FALSE binary state | -247 | | -454 | mV |
| ΔV_{OT} | Change in V_{OT} between Complimentary Output States | | | 50 | mV |
| V_{OS} | Output Common Mode Voltage (Offset Voltage) | 1.125 | 1.25 | 1.375 | V |
| ΔV_{OS} | Change in V_{OS} between Complimentary Output States | | | 50 | mV |
| I_{OS} | Outputs Short Circuit Current, V_{OUT+} or $V_{OUT-} = 0V$ or V_{DDO} | | 9 | 24 | mA |
| I_{OSD} | Differential Outputs Short Circuit Current, $V_{OUT+} = V_{OUT-}$ | | 6 | 12 | mA |

Table 16: DC Electrical Characteristics for LVDS ($V_{DDO} = 1.8V \pm 5\%$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

| Symbol | Parameter | Min | Typ | Max | Unit |
|-----------------|--|------|-------|------|------|
| $V_{OT}(+)$ | Differential Output Voltage for the TRUE binary state | 247 | | 454 | mV |
| $V_{OT}(-)$ | Differential Output Voltage for the FALSE binary state | -247 | | -454 | mV |
| ΔV_{OT} | Change in V_{OT} between Complimentary Output States | | | 50 | mV |
| V_{OS} | Output Common Mode Voltage (Offset Voltage) | 0.8 | 0.875 | 0.95 | V |
| ΔV_{OS} | Change in V_{OS} between Complimentary Output States | | | 50 | mV |
| I_{OS} | Outputs Short Circuit Current, V_{OUT+} or $V_{OUT-} = 0V$ or V_{DD} | | 9 | 24 | mA |
| I_{OSD} | Differential Outputs Short Circuit Current, $V_{OUT+} = V_{OUT-}$ | | 6 | 12 | mA |

Table 17: DC Electrical Characteristics for LVPECL ($V_{DDO} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

| Symbol | Parameter | Min | Typ | Max | Unit |
|-------------|--|------------------|-----|------------------|------|
| V_{OH} | Output Voltage HIGH, terminated through 50Ω tied to $V_{DD} - 2V$ | $V_{DDO} - 1.19$ | | $V_{DDO} - 0.69$ | V |
| V_{OL} | Output Voltage LOW, terminated through 50Ω tied to $V_{DD} - 2V$ | $V_{DDO} - 1.94$ | | $V_{DDO} - 1.4$ | V |
| V_{SWING} | Peak-to-Peak Output Voltage Swing | 0.55 | | 0.993 | V |

Table 18: Electrical Characteristics – DIF 0.7V Regular HCSL Outputs (TA = -40°C to +85°C)
(For OUT1, OUT2 and OUT4 programmable differential output pairs when configured as HCSL outputs.),

TA = T_{COM} or T_{IND}. Supply voltage per VDD of normal operation conditions; see Test Loads for loading conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|------------------------|------------------------|---|------|-----|------|-------|---------|
| Slew rate | Trf | Scope averaging on | 1 | | 4 | V/ns | 1, 2, 3 |
| Slew rate matching | ΔTrf | Slew rate matching, scope averaging on | | | 20 | % | 1, 2, 4 |
| Voltage High | V _{HIGH} | Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging on) | 660 | | 850 | mV | 1,7 |
| Voltage Low | V _{LOW} | | -150 | | 150 | | 1,7 |
| Max Voltage | V _{max} | Measurement on single ended signal using absolute value. (Scope averaging off) | | | 1150 | mV | 1 |
| Min Voltage | V _{min} | | -300 | | | | 1 |
| Vswing | Vswing | Scope averaging off | 300 | | | mV | 1,2,7 |
| Crossing Voltage (abs) | V _{cross_abs} | Scope averaging off | 250 | | 550 | mV | 1,5,7 |
| Crossing Voltage (var) | Δ-V _{cross} | Scope averaging off | | | 140 | mV | 1, 6 |

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform.

³ Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

⁴ Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

⁵ V_{cross} is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

⁶ The total variation of all V_{cross} measurements in any particular system. Note that this is a subset of V_{cross_min/max} (V_{cross} absolute) allowed. The intent is to limit V_{cross} induced modulation by setting Δ-V_{cross} to be smaller than V_{cross} absolute.

⁷ At default SMBus settings.

Table 19: Electrical Characteristics—Low Power HCSL (LP-HCSL) Outputs

(For OUT3 and OUT5–11 LP-HCSL differential output pairs.)

TA = T_{AMB}; Supply voltage per VDD, VDDIO of normal operation conditions; see Test Loads for loading conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|------------------------|------------------------|---|------|-----|------|-------|-------|
| Slew rate | t _{RF} | Scope averaging on | 1 | 2.5 | 4 | V/ns | 1,2,3 |
| Slew rate matching | dV/dt | Slew rate matching, scope averaging on | | 7 | 20 | % | 1,2,4 |
| Voltage High | V _{HIGH} | Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging on) | 660 | 0 | 850 | mV | 7 |
| Voltage Low | V _{LOW} | | -150 | 0 | 150 | | 7 |
| Max Voltage | V _{max} | Measurement on single ended signal using absolute value. (Scope averaging off) | | 0 | 1150 | mV | 7 |
| Min Voltage | V _{min} | | -300 | 0 | | | 7 |
| Vswing | Vswing | Scope averaging off | 300 | 0 | | mV | 1,2 |
| Crossing Voltage (abs) | V _{cross_abs} | Scope averaging off | 250 | 0 | 550 | mV | 1,5 |
| Crossing Voltage (var) | Δ-V _{cross} | Scope averaging off | | 0 | 140 | mV | 1,6 |

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform.

³ Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

⁴ Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

⁵ V_{cross} is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

⁶ The total variation of all V_{cross} measurements in any particular system. Note that this is a subset of V_{cross_min/max} (V_{cross absolute}) allowed. The intent is to limit V_{cross} induced modulation by setting Δ-V_{cross} to be smaller than V_{cross absolute}.

⁷ At default SMBus settings.

Table 20: AC Timing Electrical Characteristics

($V_{DDO} = 1.8V \pm 5\%$, $T_A = -40^{\circ}C$ to $+85^{\circ}C$)
(Spread Spectrum Generation = OFF)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|------------|---------------------------|--|----------------|------|------|-------|
| f_{IN}^1 | Input Frequency | Input frequency limit (XIN) | 8 | | 40 | MHz |
| | | Input frequency limit (REF) | 1 | | 200 | MHz |
| f_{OUT} | Output Frequency | Single ended clock output limit (LVCMOS) | 1 | | 200 | MHz |
| | | Differential clock output limit | 1 | | 350 | |
| f_{VCO} | VCO Frequency | VCO operating frequency range | 2500 | | 2900 | MHz |
| f_{PFD} | PFD Frequency | PFD operating frequency range | 1 ¹ | | 150 | MHz |
| f_{BW} | Loop Bandwidth | Input frequency = 25MHz | 0.06 | | 0.9 | MHz |
| t_2 | Input Duty Cycle | Duty Cycle | 45 | | 55 | % |
| t_3^5 | Output Duty Cycle | Measured at VDD/2, all outputs except Reference output OUT0, VDDOX = 2.5V or 3.3V | 45 | 50 | 55 | % |
| | | Measured at VDD/2, all outputs except Reference output OUT0, VDDOX=1.8V | 40 | 50 | 60 | % |
| | | Measured at VDD/2, Reference output OUT0 (5MHz - 120MHz) with 50% duty cycle input | 40 | 50 | 60 | % |
| | | Measured at VDD/2, Reference output OUT0 (150.1MHz - 200MHz) with 50% duty cycle input | 30 | 50 | 70 | % |
| t_4^2 | Slew Rate, SLEW[1:0] = 00 | Single-ended 3.3V LVCMOS output clock rise and fall time, 20% to 80% of VDDO (Output Load = 5 pF) VDDOX = 3.3V | 1.0 | 2.2 | | V/ns |
| | Slew Rate, SLEW[1:0] = 01 | | 1.2 | 2.3 | | |
| | Slew Rate, SLEW[1:0] = 10 | | 1.3 | 2.4 | | |
| | Slew Rate, SLEW[1:0] = 11 | | 1.7 | 2.7 | | |
| | Slew Rate, SLEW[1:0] = 00 | Single-ended 2.5V LVCMOS output clock rise and fall time, 20% to 80% of VDDO (Output Load = 5 pF) VDDOX = 2.5V | 0.6 | 1.3 | | |
| | Slew Rate, SLEW[1:0] = 01 | | 0.7 | 1.4 | | |
| | Slew Rate, SLEW[1:0] = 10 | | 0.6 | 1.4 | | |
| | Slew Rate, SLEW[1:0] = 11 | | 1.0 | 1.7 | | |
| | Slew Rate, SLEW[1:0] = 00 | Single-ended 1.8V LVCMOS output clock rise and fall time, 20% to 80% of VDDO (Output Load = 5 pF) VDDOX = 1.8V | 0.3 | 0.7 | | |
| | Slew Rate, SLEW[1:0] = 01 | | 0.4 | 0.8 | | |
| | Slew Rate, SLEW[1:0] = 10 | | 0.4 | 0.9 | | |
| | Slew Rate, SLEW[1:0] = 11 | | 0.7 | 1.2 | | |
| t_5 | Rise Times | LVDS, 20% to 80% | | 300 | | ps |
| | Fall Times | LVDS, 80% to 20% | | 300 | | |
| | Rise Times | LVPECL, 20% to 80% | | 400 | | |
| | Fall Times | LVPECL, 80% to 20% | | 400 | | |

| | | | | | | |
|-----------------|--------------------------------------|---|------|------|-----|----|
| t6 | Clock Jitter | Cycle-to-Cycle jitter (Peak-to-Peak), multiple output frequencies switching, differential outputs | | 46 | | ps |
| | | Cycle-to-Cycle jitter (Peak-to-Peak), multiple output frequencies switching, LVCMOS outputs | | 74 | | ps |
| | | RMS Phase Jitter (12kHz to 5MHz integration range) reference clock (OUT0), 25 MHz LVCMOS outputs | | 0.5 | | ps |
| | | RMS Phase Jitter (12kHz to 20MHz integration range) differential output, 25MHz crystal, 156.25MHz on OUT2, and 100MHz LP-HCSL outputs on OUT3, OUT5-11. | | 0.75 | 1.5 | ps |
| t7 | Output Skew between OUT1, OUT2, OUT4 | Skew between the same frequencies , with outputs using the same driver format and phase delay set to 0 ns. | | 75 | | ps |
| | Output Skew between OUT3 and OUT5-11 | Skew between outputs at same frequency and conditions | 49.5 | | 84 | ps |
| t8 ³ | Startup Time | PLL lock time from power-up, measured after all VDD's have raised above 90% of their target value. | | | 10 | ms |
| t9 ⁴ | Startup Time | PLL lock time from shutdown mode | | 3 | 4 | ms |

1. Practical lower frequency is determined by loop filter settings.
2. A slew rate of 2.75V/ns or greater should be selected for output frequencies of 100MHz or higher.
3. Includes loading the configuration bits from EPROM to PLL registers. It does not include EPROM programming/w rite time.
4. Actual PLL lock time depends on the loop configuration.
5. Spread Spectrum generation is off unless otherwise stated.

Table 21: PCI Express Jitter Specifications ($V_{DDO} = 1.8V \pm 5\%$, $T_A = -40^{\circ}C$ to $+85^{\circ}C$)

(For LP-HCSL(OUT3, OUT5-11) outputs)

| Symbol | Parameter | Conditions | Min | Typ | Max | PCIe Industry Specification | Units | Notes |
|--|---------------------------|---|-----|-------|-----|-----------------------------|-------|-------|
| t _j (PCIe Gen1) | Phase Jitter Peak-to-Peak | $f = 100MHz$, 25MHz crystal input evaluation band: 0Hz - Nyquist (clock frequency/2) | | 23.85 | | 86 | ps | 1,4 |
| t _{REFCLK_HF_RMS} (PCIe Gen2) | Phase Jitter RMS | $f = 100MHz$, 25MHz crystal input high band: 1.5MHz - Nyquist (clock frequency/2) | | 1.83 | | 3.1 | ps | 2,4 |
| t _{REFCLK_LF_RMS} (PCIe Gen2) | Phase Jitter RMS | $f = 100MHz$, 25MHz crystal input low band: 10kHz - 1.5MHz | | 0.54 | | 3 | ps | 2,4 |
| t _{REFCLK_RMS} (PCIe Gen3) | Phase Jitter RMS | $f = 100MHz$, 25MHz crystal input evaluation band: 0Hz - Nyquist (clock frequency/2) | | 0.51 | | 1 | ps | 3,4 |

Note: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

1. Peak-to-Peak jitter after applying system transfer function for the Common Clock Architecture. Maximum limit for PCI Express Gen 1.
2. RMS jitter after applying the two evaluation bands to the two transfer functions defined in the Common Clock Architecture and reporting the worst case results for each evaluation band. Maximum limit for PCI Express Generation 2 is 3.1ps RMS for t_{REFCLK_HF_RMS} (High Band) and 3.0ps RMS for t_{REFCLK_LF_RMS} (Low Band).
3. RMS jitter after applying system transfer function for the common clock architecture. This specification is based on the PCI_Express_Base_r3.0 10 Nov, 2010 specification, and is subject to change pending the final release version of the specification.
4. This parameter is guaranteed by characterization. Not tested in production.

Table 22: PCI Express Jitter Specifications ($V_{DDO} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $T_A = -40^\circ C$ to $+85^\circ C$)
(For regular HCSL(OUT1, OUT2 and OUT4) outputs)

| Symbol | Parameter | Conditions | Min | Typ | Max | PCIe Industry Specification | Units | Notes |
|--|---------------------------|--|-----|------|-----|-----------------------------|-------|-------|
| t_j (PCIe Gen1) | Phase Jitter Peak-to-Peak | $f = 100\text{MHz}$, 25MHz crystal input evaluation band: 0Hz - Nyquist (clock frequency/2) | | 30 | | 86 | ps | 1,4 |
| $t_{\text{REFCLK_HF_RMS}}$ (PCIe Gen2) | Phase Jitter RMS | $f = 100\text{MHz}$, 25MHz crystal input high band: 1.5MHz - Nyquist (clock frequency/2) | | 2.25 | | 3.1 | ps | 2,4 |
| $t_{\text{REFCLK_LF_RMS}}$ (PCIe Gen2) | Phase Jitter RMS | $f = 100\text{MHz}$, 25MHz crystal input low band: 10kHz - 1.5MHz | | 0.27 | | 3 | ps | 2,4 |
| $t_{\text{REFCLK_RMS}}$ (PCIe Gen3) | Phase Jitter RMS | $f = 100\text{MHz}$, 25MHz crystal input evaluation band: 0Hz - Nyquist (clock frequency/2) | | 0.8 | | 1 | ps | 3,4 |

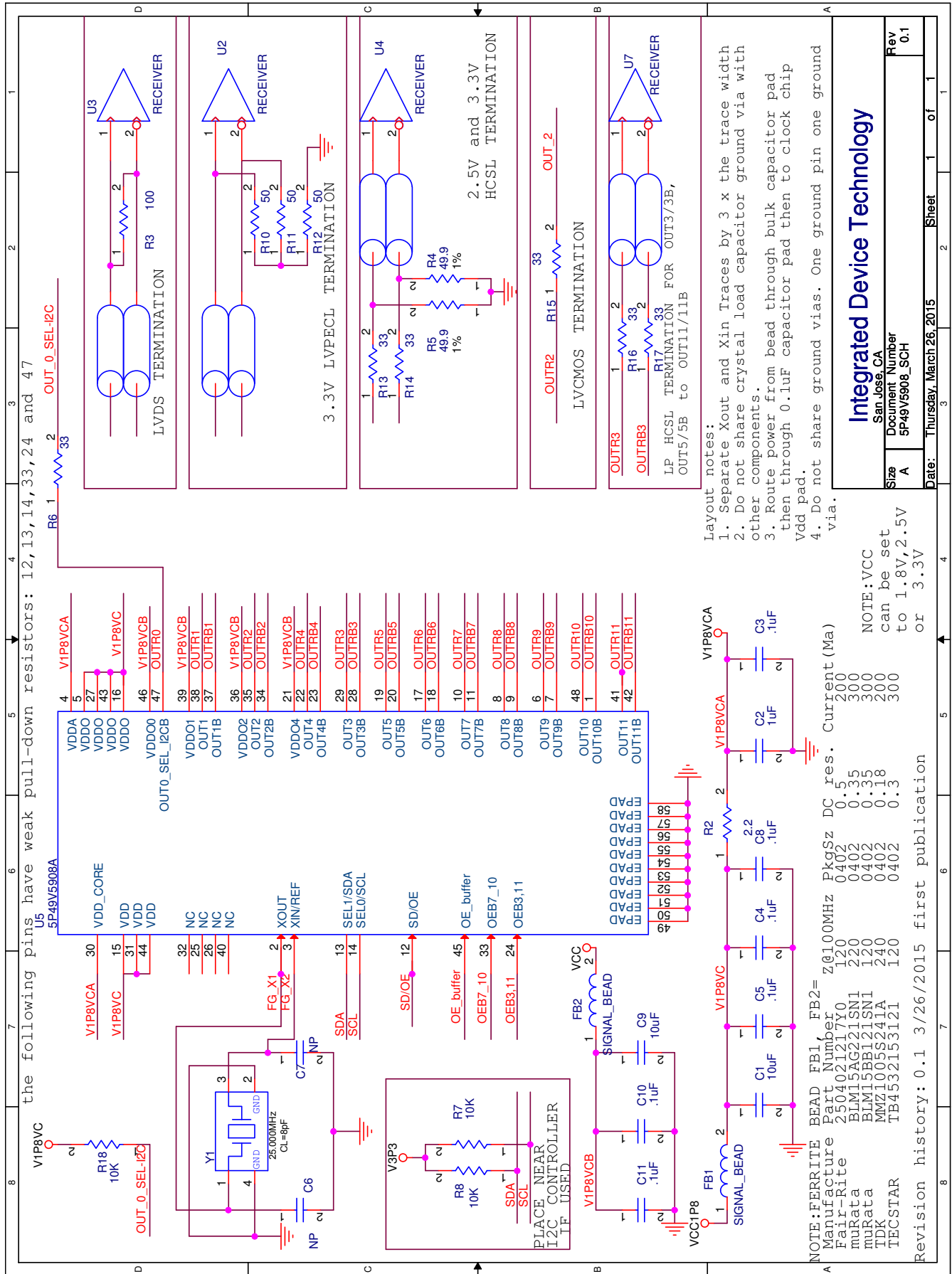
Note: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

1. Peak-to-Peak jitter after applying system transfer function for the Common Clock Architecture. Maximum limit for PCI Express Gen 1.
2. RMS jitter after applying the two evaluation bands to the two transfer functions defined in the Common Clock Architecture and reporting the worst case results for each evaluation band. Maximum limit for PCI Express Generation 2 is 3.1ps RMS for $t_{\text{REFCLK_HF_RMS}}$ (High Band) and 3.0ps RMS for $t_{\text{REFCLK_LF_RMS}}$ (Low Band).
3. RMS jitter after applying system transfer function for the common clock architecture. This specification is based on the PCI_Express_Base_r3.0 10 Nov, 2010 specification, and is subject to change pending the final release version of the specification.
4. This parameter is guaranteed by characterization. Not tested in production.

Table 23: Spread Spectrum Generation Specifications

| Symbol | Parameter | Description | Min | Typ | Max | Unit |
|---------------------|------------------|---|-----------------------------|-----|-----|--------------------|
| f_{OUT} | Output Frequency | Output frequency range | 1 | | 300 | MHz |
| f_{MOD} | Mod Frequency | Modulation frequency | 30 to 63 | | | kHz |
| f_{SPREAD} | Spread Value | Amount of spread value (programmable) - center spread | $\pm 0.25\%$ to $\pm 2.5\%$ | | | $\%f_{\text{OUT}}$ |
| | | Amount of spread value (programmable) - down spread | -0.5% to -5% | | | |

5P49V5908 Reference Schematic



the following pins have weak pull-down resistors: 12,13,14,33,24 and 47

Layout notes:
 1. Separate Xout and Xin Traces by 3 x the trace width
 2. Do not share crystal load capacitor ground via with other components.
 3. Route power from bead through bulk capacitor pad then through 0.1uF capacitor pad then to clock chip vdd pad.
 4. Do not share ground vias. One ground pin one ground via.

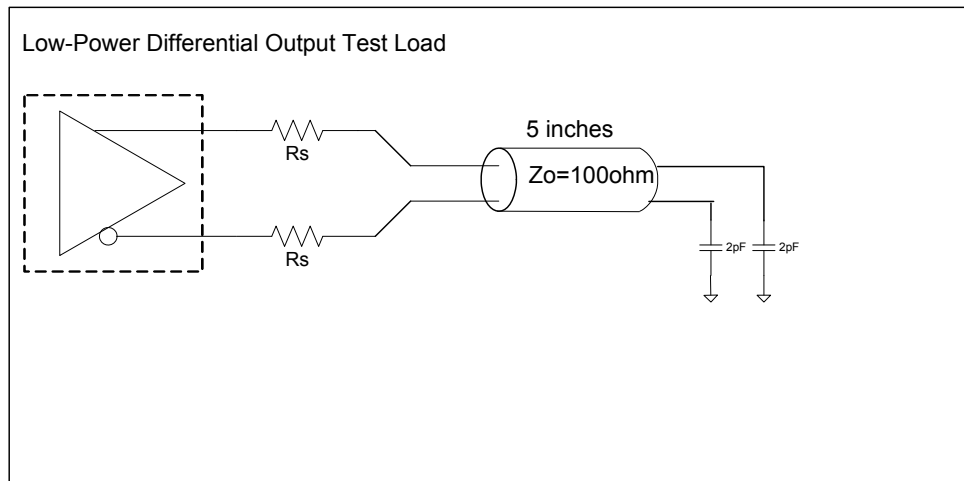
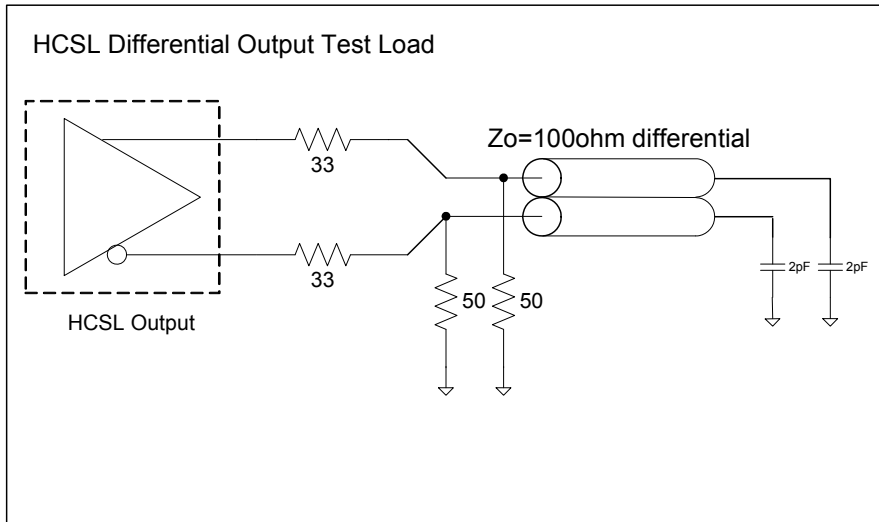
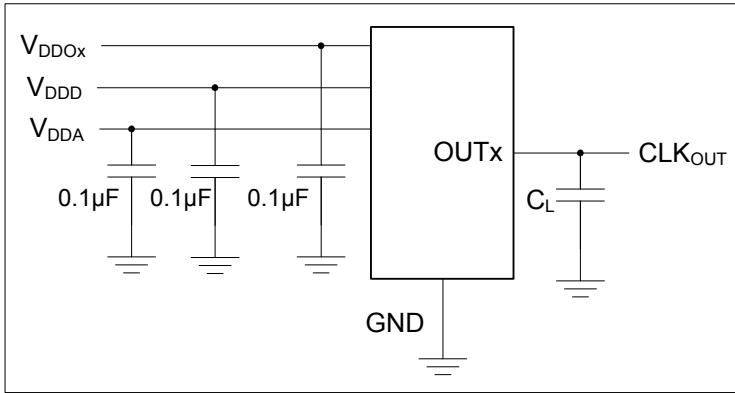
| | |
|-------------------------------------|--------------------------|
| Integrated Device Technology | |
| San Jose CA | |
| Document Number | 5P49V5908_SCH |
| Size | A |
| Rev | 0.1 |
| Date: | Thursday, March 26, 2015 |
| Sheet | 1 of 1 |

NOTE: FERRITE BEAD FB1, FB2=

| Manufacturer | Part Number | z@100MHz | Pkgsz | DC res. | Current (Ma) |
|--------------|---------------|----------|-------|---------|--------------|
| Fair-Rite | 2504021217Y0 | 120 | 0402 | 0.5 | 200 |
| muRata | BLM15AG221SN1 | 220 | 0402 | 0.35 | 300 |
| muRata | BLM15BB121SN1 | 120 | 0402 | 0.35 | 300 |
| TDK | MWZ1005S24TA | 240 | 0402 | 0.18 | 200 |
| TECSTAR | 1B4532153121 | 120 | 0402 | 0.3 | 300 |

Revision history: 0.1 3/26/2015 first publication

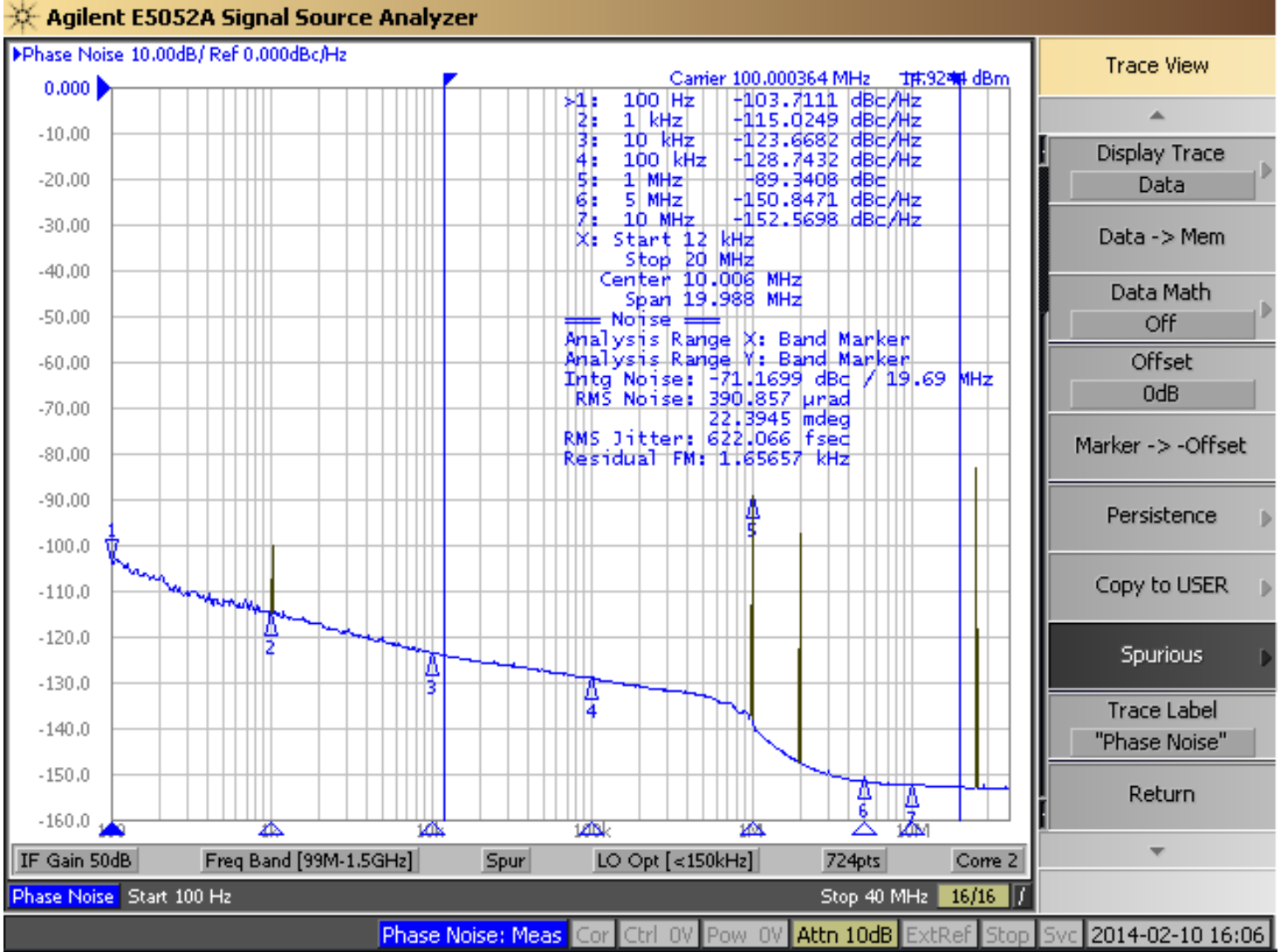
Test Circuits and Loads



Alternate Differential Output Terminations

| R_s | Z_o | Units |
|-------|-------|-------|
| 33 | 100 | Ohms |
| 27 | 85 | |

Typical Phase Noise at 100MHz (3.3V, 25°C)



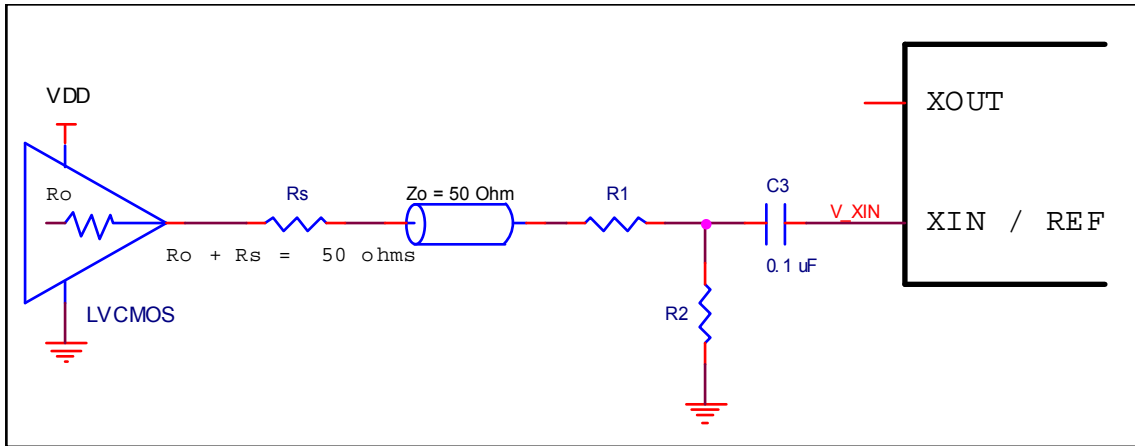
NOTE: All outputs operational at 100MHz, Phase Noise Plot with Spurs On.

Overdriving the XIN/REF Interface

LVC MOS Driver

The XIN/REF input can be overdriven by an LVC MOS driver or by one side of a differential driver through an AC coupling capacitor. The XOUT pin can be left floating. The amplitude of the input signal should be between 500mV and 1.2V and the slew rate should not be less than 0.2V/ns. Figure General Diagram for LVC MOS Driver to XTAL Input Interface shows an example of the interface diagram for a LVC MOS driver.

This configuration has three properties; the total output impedance of R_o and R_s matches the 50 ohm transmission line impedance, the V_{rx} voltage is generated at the CLKIN inputs which maintains the LVC MOS driver voltage level across the transmission line for best S/N and the R_1 - R_2 voltage divider values ensure that the clock level at XIN is less than the maximum value of 1.2V.



General Diagram for LVC MOS Driver to XTAL Input Interface

[Table 24](#) *Nominal Voltage Divider Values vs LVC MOS VDD for XIN* shows resistor values that ensure the maximum drive level for the XIN/REF port is not exceeded for all combinations of 5% tolerance on the driver VDD, the VersaClock VDDA and 5% resistor tolerances. The values of the resistors can be

adjusted to reduce the loading for slower and weaker LVC MOS driver by increasing the voltage divider attenuation as long as the minimum drive level is maintained over all tolerances. To assist this assessment, the total load on the driver is included in the table.

Table 24: Nominal Voltage Divider Values vs LVC MOS VDD for XIN

| LVC MOS Driver VDD | R_o+R_s | R_1 | R_2 | V_{XIN} (peak) | $R_o+R_s+R_1+R_2$ |
|--------------------|-----------|-------|-------|------------------|-------------------|
| 3.3 | 50.0 | 130 | 75 | 0.97 | 255 |
| 2.5 | 50.0 | 100 | 100 | 1.00 | 250 |
| 1.8 | 50.0 | 62 | 130 | 0.97 | 242 |

LVPECL Driver

Figure *General Diagram for LVPECL Driver to XTAL Input Interface* shows an example of the interface diagram for a +3.3V LVPECL driver. This is a standard LVPECL termination with one side of the driver feeding the XIN/REF input. It is recommended that all components in the schematics be placed in the layout; though some components might not be

used, they can be utilized for debugging purposes. The datasheet specifications are characterized and guaranteed by using a quartz crystal as the input. If the driver is 2.5V LVPECL, the only change necessary is to use the appropriate value of R3.

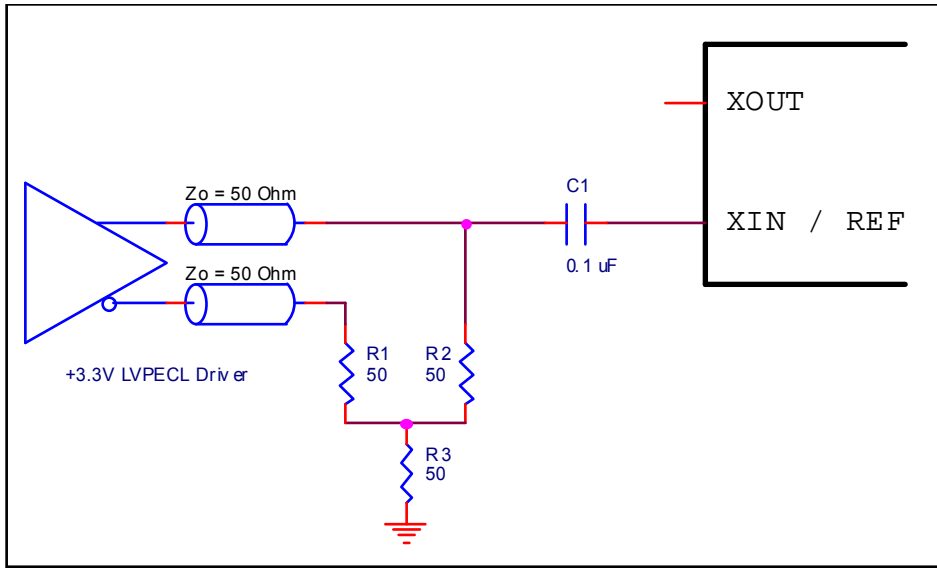


Table 25 *Nominal Voltage Divider Values vs Driver VDD* shows resistor values that ensure the maximum drive level for the CLKIN port is not exceeded for all combinations of 5% tolerance on the driver VDD, the VersaClock Vddo_0 and 5% resistor tolerances. The values of the resistors can be

adjusted to reduce the loading for slower and weaker LVCMOS driver by increasing the impedance of the R1-R2 divider. To assist this assessment, the total load on the driver is included in the table.

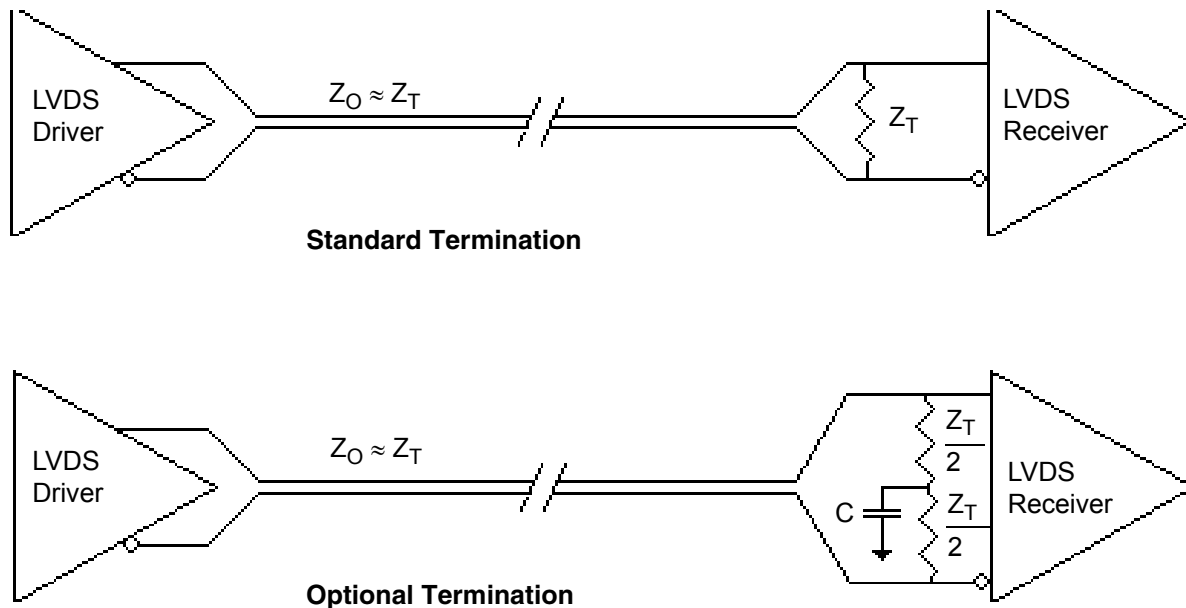
Table 25: Nominal Voltage Divider Values vs Driver VDD

| LVC MOS Driver VDD | Ro+Rs | R1 | R2 | Vrx (peak) | Ro+Rs+R1+R2 |
|--------------------|-------|-----|-----|------------|-------------|
| 3.3 | 50.0 | 130 | 75 | 0.97 | 255 |
| 2.5 | 50.0 | 100 | 100 | 1.00 | 250 |
| 1.8 | 50.0 | 62 | 130 | 0.97 | 242 |

LVDS Driver Termination

For a general LVDS interface, the recommended value for the termination impedance (Z_T) is between 90Ω and 132Ω . The actual value should be selected to match the differential impedance (Z_0) of your transmission line. A typical point-to-point LVDS design uses a 100Ω parallel resistor at the receiver and a 100Ω differential transmission-line environment. In order to avoid any transmission-line reflection issues, the components should be surface mounted and must be placed as close to the receiver as possible. The standard termination schematic as shown in figure *Standard Termination* or the termination of figure *Optional Termination* can be used, which uses a center tap capacitance to help filter

common mode noise. The capacitor value should be approximately 50pF . In addition, since these outputs are LVDS compatible, the input receiver's amplitude and common-mode input range should be verified for compatibility with the IDT LVDS output. If using a non-standard termination, it is recommended to contact IDT and confirm that the termination will function as intended. For example, the LVDS outputs cannot be AC coupled by placing capacitors between the LVDS outputs and the 100Ω shunt load. If AC coupling is required, the coupling caps must be placed between the 100Ω shunt termination and the receiver. In this manner the termination of the LVDS output remains DC coupled



PCI Express Application Note

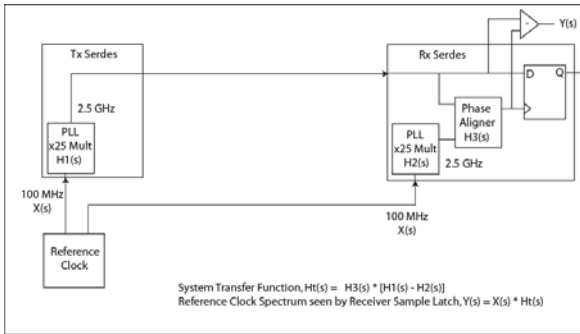
PCI Express jitter analysis methodology models the system response to reference clock jitter. The block diagram below shows the most frequently used Common Clock Architecture in which a copy of the reference clock is provided to both ends of the PCI Express Link. In the jitter analysis, the transmit (Tx) and receive (Rx) serdes PLLs are modeled as well as the phase interpolator in the receiver. These transfer functions are called H1, H2, and H3 respectively. The overall system transfer function at the receiver is:

$$H_t(s) = H_3(s) \times [H_1(s) - H_2(s)]$$

The jitter spectrum seen by the receiver is the result of applying this system transfer function to the clock spectrum X(s) and is:

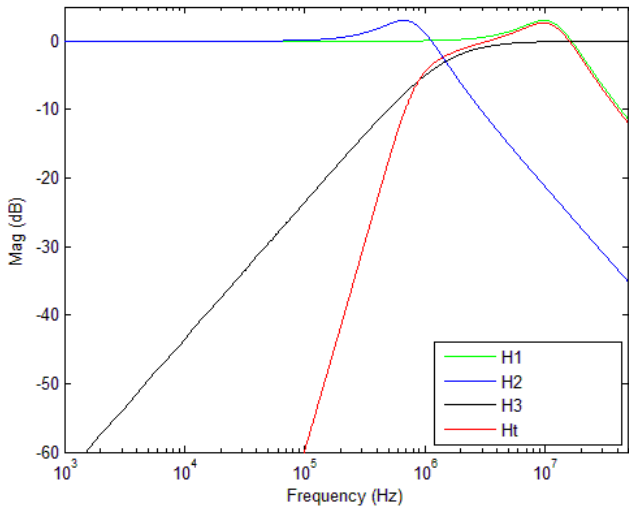
$$Y(s) = X(s) \times H_3(s) \times [H_1(s) - H_2(s)]$$

In order to generate time domain jitter numbers, an inverse Fourier Transform is performed on X(s)*H3(s) * [H1(s) - H2(s)].



PCI Express Common Clock Architecture

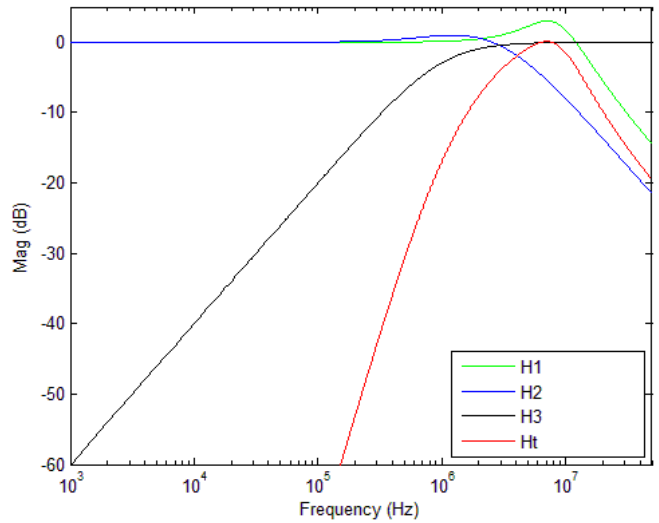
For PCI Express Gen 1, one transfer function is defined and the evaluation is performed over the entire spectrum: DC to Nyquist (e.g for a 100MHz reference clock: 0Hz – 50MHz) and the jitter result is reported in peak-peak.



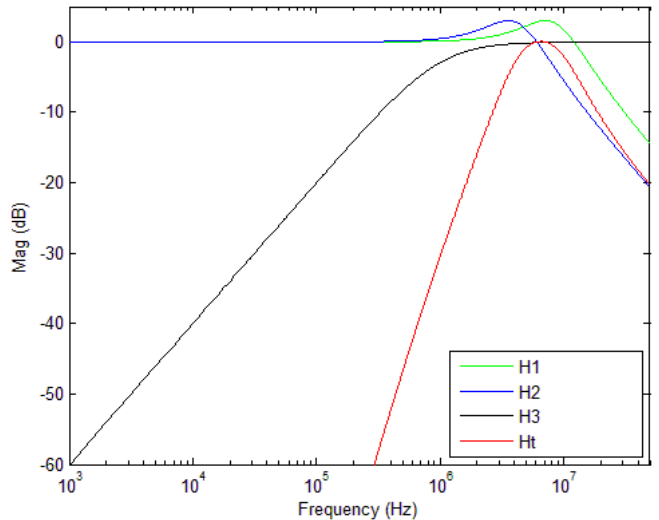
PCI Express Gen1 Magnitude of Transfer Function

For PCI Express Gen2, two transfer functions are defined with 2 evaluation ranges and the final jitter number is reported in

RMS. The two evaluation ranges for PCI Express Gen 2 are 10kHz – 1.5MHz (Low Band) and 1.5MHz – Nyquist (High Band). The plots show the individual transfer functions as well as the overall transfer function Ht.

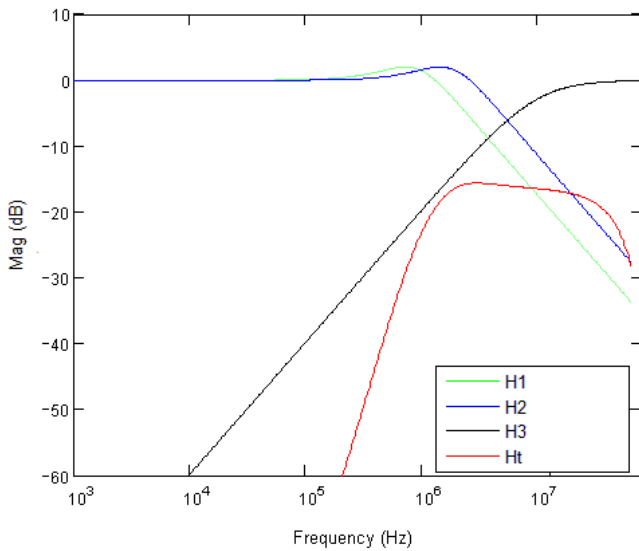


PCIe Gen2A Magnitude of Transfer Function



PCIe Gen2B Magnitude of Transfer Function

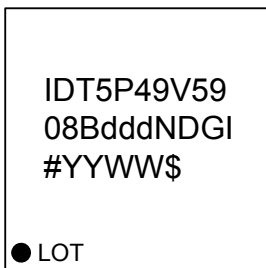
For PCI Express Gen 3, one transfer function is defined and the evaluation is performed over the entire spectrum. The transfer function parameters are different from Gen 1 and the jitter result is reported in RMS.



PCIe Gen3 Magnitude of Transfer Function

For a more thorough overview of PCI Express jitter analysis methodology, please refer to IDT Application Note PCI Express Reference Clock Requirements.

Marking Diagram



1. “ddd” denotes the dash code.
2. “G” denotes RoHS compliance.
3. “I” denotes industrial temperature.
4. “YYWW” is the two last digits of the year and week that the part was assembled.
5. “#” denotes the stepping code.
6. “\$” denotes mark code.
7. “LOT” denotes lot number.

Package Outline and Dimensions NDG48 (48-pin VFQFN)

| REVISIONS | | | |
|-----------|-----------------|----------|----------|
| REV | DESCRIPTION | DATE | APPROVED |
| 00 | INITIAL RELEASE | 01/06/16 | JH |
| 01 | ADD CHAMFER | 09/14/16 | JH |

TOP VIEW

SIDE VIEW

BOTTOM VIEW

| SYMBOL | DIMENSION | | |
|--------|------------------|------|------|
| | MIN | NOM | MAX |
| D2 | 4.10 | 4.20 | 4.30 |
| E2 | 4.10 | 4.20 | 4.30 |
| L | 0.35 | 0.40 | 0.45 |
| K | 0.50 REF. | | |
| D | 6.00 BSC. | | |
| E | 6.00 BSC. | | |
| e | 0.40 BSC. | | |
| A | 0.80 | 0.90 | 1.00 |
| A1 | 0.00 | 0.02 | 0.05 |
| A3 | --- 0.20 REF --- | | |
| N | 48 | | |
| ND | 12 | | |
| NE | 12 | | |
| b | 0.15 | 0.20 | 0.25 |

| TOLERANCES UNLESS SPECIFIED | |
|-----------------------------|---------|
| DECIMAL | ANGULAR |
| XX.X | ±1° |
| XX.XX | |
| XXX.X | |
| XXX.XX | |

| APPROVALS | DATE |
|-------------------|----------|
| DRAWN: β 4C | 01/06/16 |
| CHECKED: | |

| | |
|--|-----------------------------------|
| 6024 Silver Creek Valley Road San Jose, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-8581 WWW.IDT.COM | |
| TITLE: ND/NDG 48 PACKAGE OUTLINE 6.0 x 6.0 mm BODY 0.40 mm PITCH QFN | DRAWING No. PSC-4212-02 REV 01 |

DO NOT SCALE DRAWING SHEET 1 OF 2

NOTES:

- ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- ALL DIMENSIONS ARE IN MILLIMETERS.
- N REFERS TO THE NUMBER OF LEADS.
- ND AND NE REFER TO THE NUMBER OF LEADS PER SIDE.

Package Outline and Dimensions NDG48 (48-pin VFQFN), cont.

| REVISIONS | | |
|-----------|-----------------|----------|
| REV | DESCRIPTION | DATE |
| 00 | INITIAL RELEASE | 01/06/16 |
| 01 | ADD CHAMFER | 09/14/16 |

RECOMMENDED LAND PATTERN DIMENSION

NOTES:

1. ALL DIMENSION ARE IN mm. ANGLES IN DEGREES.
2. TOP DOWN VIEW, AS VIEWED ON PCB.
3. COMPONENT OUTLINE SHOW FOR REFERENCE IN GREEN.
4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

| | |
|--|---|
| IDT™ 6024 Silver Creek Valley Road San Jose CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-8591 www.IDT.com | |
| TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR XX± XXX± | TITLE ND/NDG 48 PACKAGE OUTLINE 6.0 x 6.0 mm BODY 0.40 mm PITCH QFN |
| APPROVALS DRAWN: <i>Ø4G</i> DATE: 01/06/16 CHECKED: | SIZE: C DRAWING No. PSC-4212-02 REV: 01 |
| DO NOT SCALE DRAWING SHEET 2 OF 2 | |

Ordering Information

| Part / Order Number | Shipping Packaging | Package | Temperature |
|---------------------|--------------------|---------------|---------------|
| 5P49V5908BdddNDGI | Trays | 48-pin VFQFPN | -40° to +85°C |
| 5P49V5908BdddNDGI8 | Tape and Reel | 48-pin VFQFPN | -40° to +85°C |

“ddd” denotes the dash code.

“G” after the two-letter package code denotes Pb-Free configuration, RoHS compliant.

Revision History

| Date | Description of Change |
|-------------------|---|
| March 10, 2017 | <ol style="list-style-type: none"> 1. Updated package outline drawings. 2. Updated legal disclaimer. 3. Corrected typos. |
| February 24, 2017 | <ol style="list-style-type: none"> 1. Added “Output Alignment” section. 2. Update “Output Divides” section |



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